

Material Declaration Data Sheet

Customer : Nordic
Device : nRF52832
Wafer Drawing # : D002555
Drawing Rev : C
Unit Drawing # : D002554
Drawing Rev : A

| Material | Purpose | Substance Composition | CAS Number | Weight by mg | % weight of substance per Homogenous material | PPM | % weight of substance per package |
|-----------------------------|--------------|-----------------------|------------|---------------|---|--------|-----------------------------------|
| Polybenzoxazole1 | Dielectric | Proprietary | ----- | 0.0710 | 100.00% | 7821 | 0.78% |
| Polybenzoxazole2 | Dielectric | Proprietary | ----- | 0.0603 | 100.00% | 6650 | 0.67% |
| RDL Seed Layer | Seed Layer | Ti | 7440-32-6 | 0.0004 | 3.93% | 46 | 0.00% |
| | Seed Layer | W | 7440-33-7 | 0.0038 | 35.40% | 416 | 0.04% |
| | Seed Layer | Cu | 7440-50-8 | 0.0065 | 60.67% | 713 | 0.07% |
| Copper | Interconnect | Cu | 7440-50-8 | 0.1294 | 100.00% | 14258 | 1.43% |
| UBM Seed Layer | Seed Layer | Ti | 7440-32-6 | 0.0002 | 3.93% | 23 | 0.00% |
| | Seed Layer | W | 7440-33-7 | 0.0019 | 35.40% | 208 | 0.02% |
| | Seed Layer | Cu | 7440-50-8 | 0.0032 | 60.67% | 357 | 0.04% |
| Copper | UBM | Cu | 7440-50-8 | 0.1459 | 100.00% | 16077 | 1.61% |
| Solder Ball | Interconnect | Sn | 7440-31-5 | 1.4803 | 95.50% | 163120 | 16.31% |
| | Interconnect | Ag | 7440-22-4 | 0.0620 | 4.00% | 6832 | 0.68% |
| | Interconnect | Cu | 7440-50-8 | 0.0078 | 0.50% | 854 | 0.09% |
| Die | Circuit | Si | 7440-21-3 | 6.7548 | 100.00% | 744370 | 74.44% |
| Top Surface Laminate | Mark Surface | Proprietary | ----- | 0.3471 | 100.00% | 38253 | 3.83% |
| Package Weight (mg): | | | | 9.0746 | % Total: | | 100.0% |

Disclaimer:

Nepes hayyim believes this information to be correct, but cannot guarantee its completeness or accuracy. The information is based on data received from sources outside our company. The information is based on data received from sources outside our company.

*NOTE : ** LC2850 is not used for this device at nepes hayyim Corporation. considering 305um Die thickness after BKG*